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UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

USAMI, Tatsuya

Serial No.: 09/627,418

Group Art Unit: 2814

Filed: July 27, 2000

Examiner: Quach, T.

For: SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE
SAME

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.111

RECEIVED
FRI 15 2001
TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action dated August 14, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 6-13 without prejudice or disclaimer.

Please revise claims 2 - 5 to read as follows.

2. (Amended) The semiconductor device according to claim 1, wherein said insulating layer comprises HSQ (Hydrogen Silsesquioxane).

3. (Amended) The semiconductor device according to claim 2, further comprising at least one adhesion layer formed in an interface between said plurality of wiring lines and said insulating layer and allowing said plurality of wiring lines and said insulating layer to adhere to one

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